

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC010N04LS	**Issued**	27. April 2022
MA#	MA005737567		
Package	PG-TDSON-8-48	**Weight***	107.89 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.517	1.41	1.41	14063	14063
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		133	
	non noble metal	zinc	7440-66-6	0.057	0.05		531	
	non noble metal	iron	7439-89-6	1.145	1.06		10614	
	non noble metal	copper	7440-50-8	46.496	43.09	44.21	430967	442245
wire	noble metal	gold	7440-57-5	0.041	0.04	0.04	382	382
encapsulation	organic material	carbon black	1333-86-4	0.080	0.07		740	
	plastics	epoxy resin	-	6.311	5.85		58493	
	inorganic material	silicondioxide	60676-86-0	33.551	31.10	37.02	310978	370211
leadfinish	non noble metal	tin	7440-31-5	1.264	1.17	1.17	11713	11713
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	269	269
solder	noble metal	silver	7440-22-4	0.052	0.05		478	
	non noble metal	tin	7440-31-5	0.103	0.10		956	
	non noble metal	lead	7439-92-1	1.907	1.77	1.92	17680	19114
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			43	
	non noble metal	zinc	7440-66-6	0.018	0.02		170	
	non noble metal	iron	7439-89-6	0.368	0.34		3408	
	non noble metal	copper	7440-50-8	14.930	13.84	14.20	138382	142003
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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